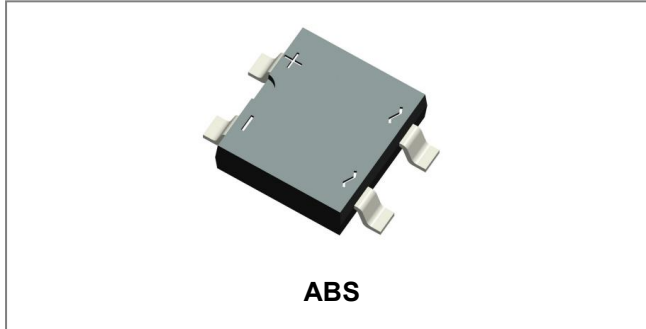


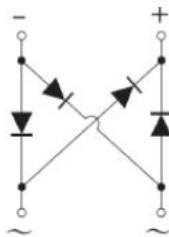
**FTB6F-15FP THRU FTB10F-15FP
1.5A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER**



Features

- Glass Passivated Chip Junction
- Reverse Voltage - 600 to 1000 V
- Forward Current - 1.5 A
- Designed for Surface Mount Application
- Fast reverse recovery time
- This is a Halogen Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: ABS
- Terminals: Solderable per MIL-STD-750, Method 2026
- Weight: 88 mg

Maximum Ratings @ $T_A=25^{\circ}C$ unless otherwise specified

Single Phase half wave 60Hz, resistive or inductive load. For capacitive load current derate by 20%.

Characteristic	Symbol	FTB6F -15FP	FTB8F -15FP	FTB10F -15FP	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	600	800	1000	V
RMS Reverse Voltage	V_{RMS}	420	560	700	V
Average Forward Output Current @ $T_A=75^{\circ}C$	$I_{F(AV)}$	1.5			A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50			A

Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

Characteristic	Symbol	FTB6F -15FP	FTB8F -15FP	FTB10F -15FP	Units
Forward voltage per element @ $I_F = 1.5\text{A}$	V_F	1.3			V
Maximum DC reverse current at rated DC blocking voltage $T_A = 25^{\circ}\text{C}$ $T_A = 125^{\circ}\text{C}$	I_R	5 50			μA
Typical Junction Capacitance (Note 1)	C_J	35			pF
Maximum Reverse Recovery Time (Note 3)	T_{rr}	160			ns

* Pulse width < 300 μs , duty cycle < 2%

Thermal-Mechanical Specifications @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

Characteristic	Symbol	FTB6F -15FP	FTB8F -15FP	FTB10F -15FP	Units
Typical Thermal Resistance (Note 2)	$R_{\theta JA}$	75			$^{\circ}\text{C}/\text{W}$
Operating and storage temperature range	T_J, T_{STG}	-55 to +150			$^{\circ}\text{C}$

Note: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.
2. Mounted on glass epoxy PC board with $4 \times (5 \times 5\text{mm}^2)$ copper pad.
3. Reverse Recovery Test Conditions: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $IRR=0.25\text{A}$

Ratings and Characteristics Curves

Fig.1 Forward Current Derating Curve

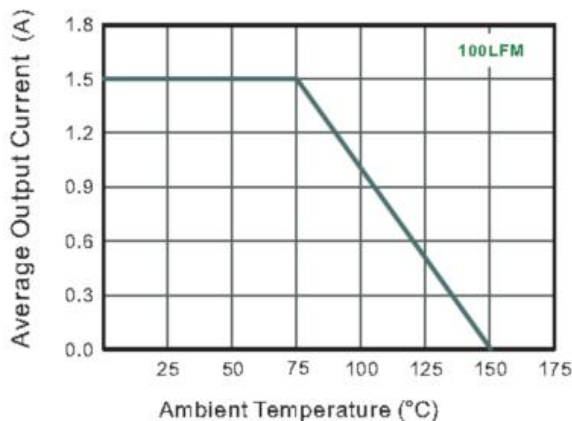


Fig.2 Typical Reverse Characteristics

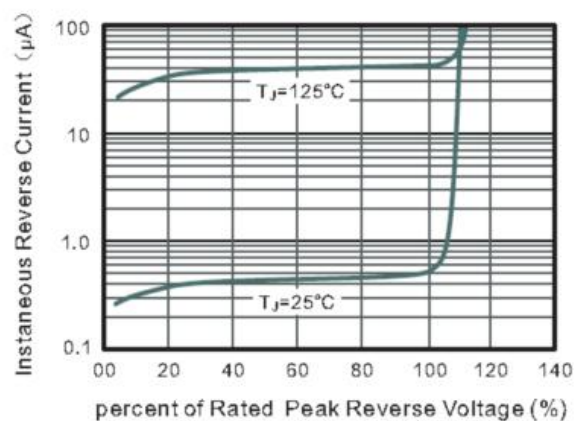


Fig.3 Typical Instantaneous Forward Characteristics

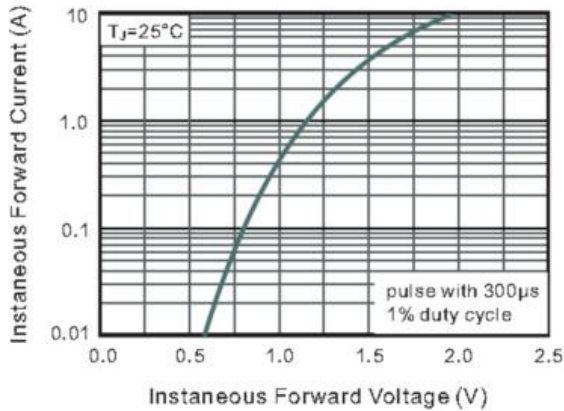


Fig.4 Typical Junction Capacitance

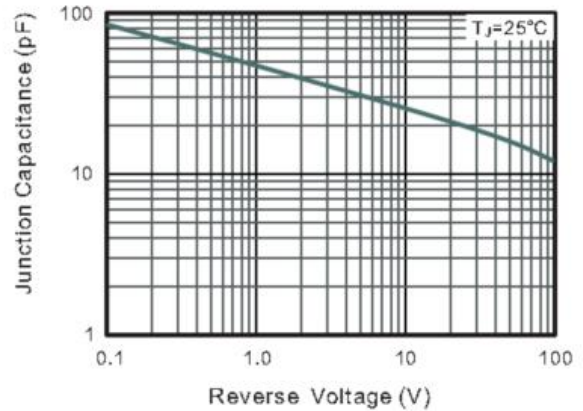
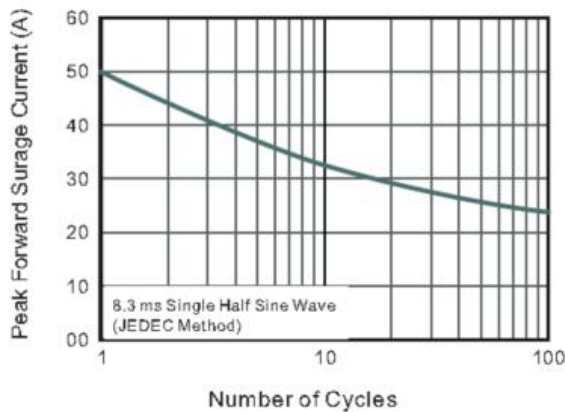


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



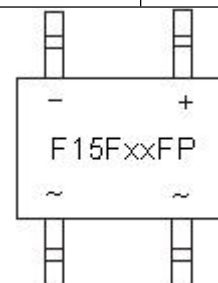
Ordering Information

Device	Package	Plating	Shipping
FTB6F-15FP THRU FTB10F-15FP	ABS	Pure Sn	5000pcs / reel

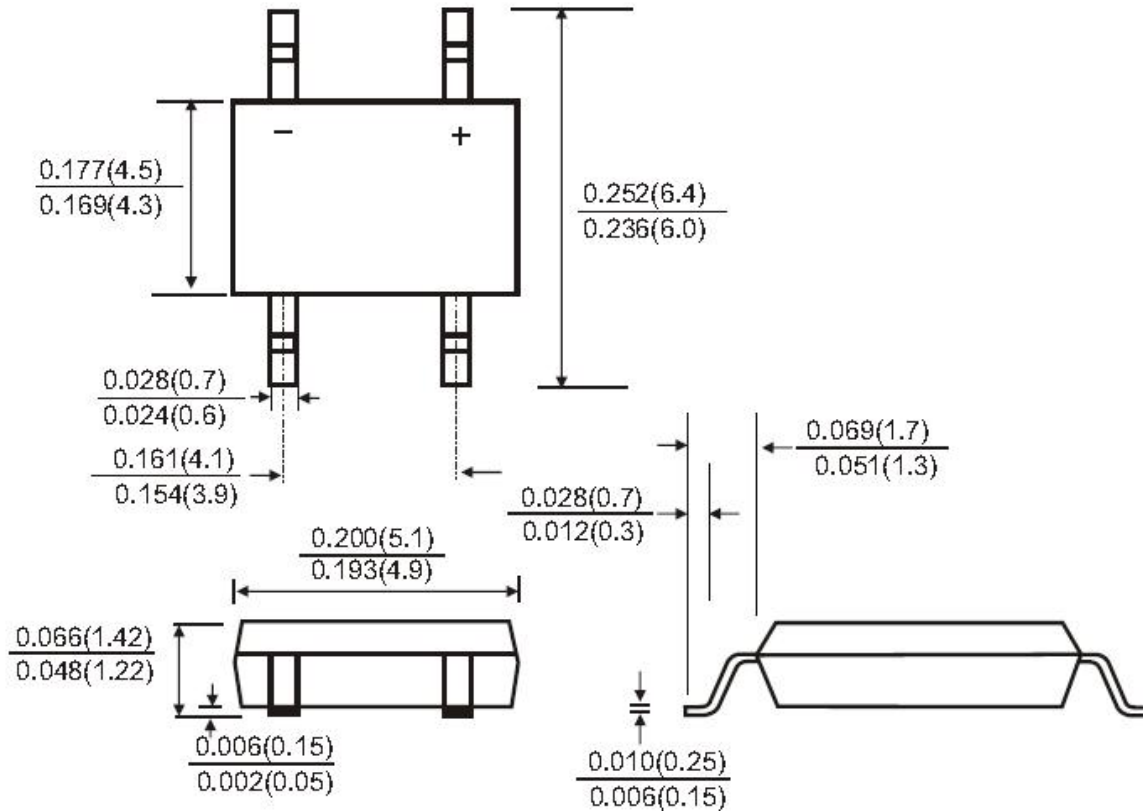
For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram

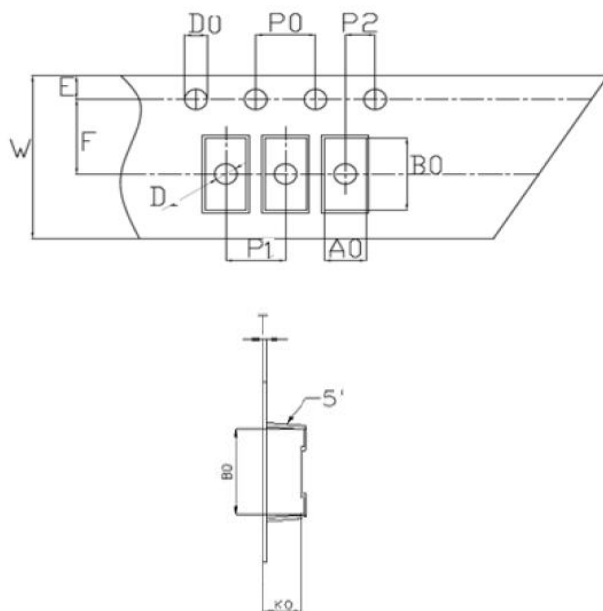
Type number	Marking code
FTB6F-15FP	F15F6FP
FTB8F-15FP	F15F8FP
FTB10F-15FP	F15F10FP



Mechanical Dimensions ABS(Inches/Millimeters)



Carrier Tape Specification ABS



SYMBOL	Millimeters	
	Min.	Max.
A0	5.21	5.41
B0	7.10	7.30
D0	1.50	1.60
D1	1.40	1.60
P0	3.90	4.10
P1	7.90	8.10
P2	1.95	2.05
E	1.65	1.85
K0	1.55	1.75
F	5.45	5.55
W	11.90	12.10
T	0.24	0.30
10P0	39.80	40.20

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